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IWANAGA SHOICHI**(54) CERAMIC COMPOSITION AND CERAMIC CIRCUIT BOARD****(57)Abstract:**

**PURPOSE:** To obtain a ceramic compsn. sinterable at a low temp., ensuring a coefft. of thermal expansion close to that of Si, a low relative dielectric constant and high strength and giving a substrate for mounting an integrated circuit.

**CONSTITUTION:** This ceramic compsn. consists of 47-63wt.% (55-70vol.%) borosilicate glass, 8-44wt.% (5-30vol.%) alumina as a filler, 5-37wt.% (5-35vol.%) cordierite and 0-18wt.% (0-20vol.%) quartz glass. When a ceramic circuit board is made of this ceramic compsn. an Si semiconductor device can be mounted with high reliability and high-speed signal propagation is enabled.

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